



### Major Ratings and Characteristics

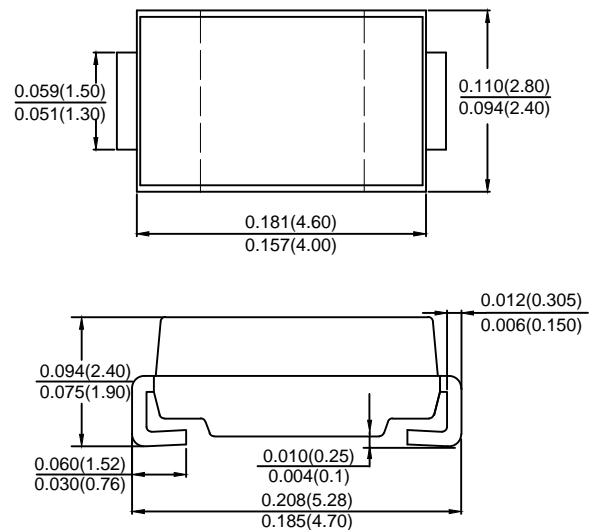
$I_{F(AV)}$	3.0 A
$V_{RRM}$	20 V to 200 V
$I_{FSM}$	70A,100 A
$V_F$	0.55V,0.7V,0.85V,0.95V
$T_j \text{ max.}$	150 °C

### SM/DO-214AC



### Features

- Low profile package
- Ideal for automated placement
- Ultrafast reverse recovery time
- Low power losses, high efficiency
- Low forward voltage drop
- High surge capability
- High temperature soldering:  
260°C/10 seconds at terminals
- Component in accordance to  
RoHS 2002/95/1 and WEEE 2002/96/EC



Dimensions in inches and (millimeters)

### Mechanical Date

- **Case:** JEDEC DO-214AC (SMA) molded plastic
- **Terminals:** Solder plated, solderable per J-STD-002B and JESD22-B102D
- **Polarity:** Laser band denotes cathode end

Type Number	Symbol	SS32	SS34	SS36	SS38	SS310	SS3150	SS3200	Unit	
Maximum Repetitive Peak Reverse Voltage	$V_{RRM}$	20	40	60	80	100	150	200	V	
Maximum RMS Voltage	$V_{RMS}$	14	28	42	56	70	105	130	V	
Maximum DC Blocking Voltage	$V_{DC}$	20	40	60	80	100	150	200	V	
Maximum Average Forward Rectified Current	$I_{F(AV)}$	3.0							A	
Peak Forward Surge Current, 8.3 ms Single Half Sine-wave Superimposed on Rated Load (JEDEC method)	$I_{FSM}$	100			70				A	
Maximum Instantaneous Forward Voltage (Note 1) @ 3.0A $T_A=25^\circ\text{C}$ $T_A=100^\circ\text{C}$ $T_A=125^\circ\text{C}$	$V_F$	0.55 0.4	0.70 0.65	0.85 0.70	0.95 0.80				V	
Maximum Reverse Current @ Rated VR $T_A=25^\circ\text{C}$ $T_A=100^\circ\text{C}$ $T_A=125^\circ\text{C}$	$I_R$	0.5			0.1				mA	
		10	5		-					
		-			0.5					
Typical Thermal Resistance	$R_{\theta JL}$ $R_{\theta JA}$	17				55				°C/W
Operating Temperature Range	$T_J$	- 55 to + 125			- 55 to + 150				°C	
Storage Temperature Range	$T_{STG}$	- 55 to + 150								°C

Note 1: Pluse Test with PW=300 usec, 1% Duty Cycle



# SS32~SS3200

## Surface Mount Schottky Rectifiers

### Characteristic Curves ( $T_A=25^\circ\text{C}$ unless otherwise noted)

FIG.1 FORWARD CURRENT DERATING CURVE

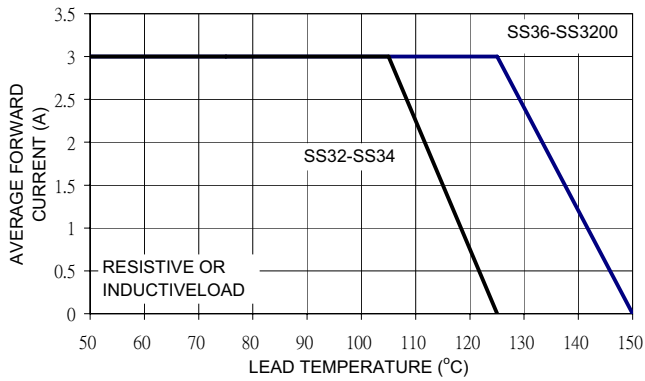


FIG. 2 MAXIMUM NON-REPETITIVE FORWARD SURGE CURRENT

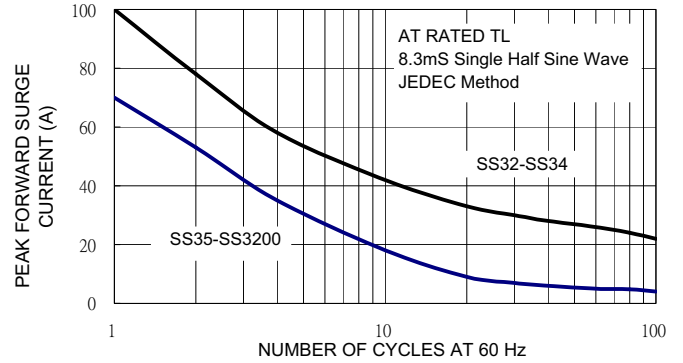


FIG. 3 TYPICAL FORWARD CHARACTERISTICS

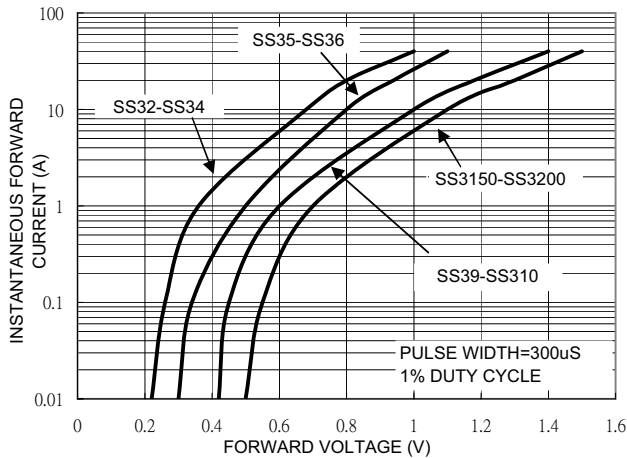


FIG. 4 TYPICAL REVERSE CHARACTERISTICS

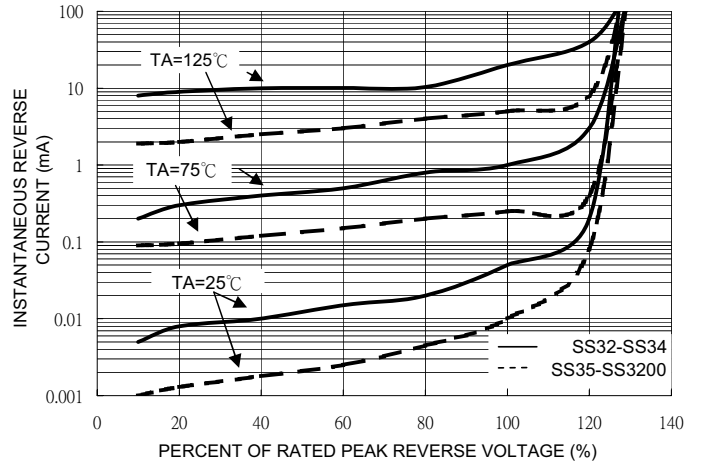


FIG. 5 TYPICAL JUNCTION CAPACITANCE

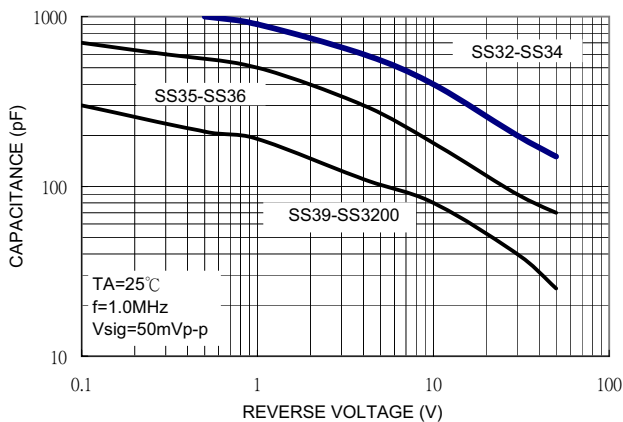


FIG. 6 TYPICAL TRANSIENT THERMAL IMPEDANCE

